

Appl. No. 10/659,415
Amtd. dated April 4, 2006
Reply to Office action of Jan. 18, 2006

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of the Claims:

1-8. (canceled)

9. (original) A system for stud bumping, comprising:

 a bonding head having a plurality of wire passages formed therein;

 a plurality of wires disposed through respective ones of the plurality of wire passages;

 a substrate having a plurality of bond pads; and

 a robot coupled to the bonding head, the robot operable to form a first set of stud bumps outwardly from respective ones of a first set of the bond pads.

10. (original) The system of Claim 9, wherein the bonding head is formed from a ceramic.

11. (original) The system of Claim 9, wherein the wires are formed from a material selected from the group consisting of gold and aluminum.

12. (original) The system of Claim 9, wherein a pitch between any two adjacent wire passages is no more than 1000 microns.

13. (original) The system of Claim 9, wherein a pitch between any two adjacent wire passages is no more than 200 microns.

14. (original) The system of Claim 9, wherein the wire passages resemble an array selected from the group consisting of a linear array and a rectangular array.

15. (original) The system of Claim 9, wherein the robot is operable to simultaneously engage the wires with respective ones of the bond pads to form the stud bumps.

16-20. (canceled)

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